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[SAMTEC LOGO]

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Samtec Features Latest 32 GT/s Interconnect Solutions at PCI-SIG® Developers Conference Asia-Pacific Tour 2019

New Albany, IN: Samtec Inc., a privately held \$822 MM global manufacturer of a broad line of electronic interconnect solutions, will showcase and demonstrate their latest high-performance interconnect and technologies at the PCI-SIG® Developers Conference Asia-Pacific Tour 2019.

Samtec high-speed technologies for Silicon-to-Silicon optimization will be on display, including new high-speed, high-bandwidth optical, board-to-board and cable-to-board interconnects. 56 Gbps PAM4 and 32 GT/s product demonstrations and technical sessions will also be highlighted.

Demonstrations:

- **Scalable 32 GT/s Silicon Test Platform:** Demonstration of configurable, next-generation GPU-based system combining cable mesh backplane (AcceleRate® Slim Body Cable Assemblies) and tradition two-connector backplane (next-generation Edge Rate® High-Speed Edge Card Connector) topologies.
- **Direct Connect Technology:** The demonstration platform showcases low latency, high performance, on-board optical engines transmitting at 56 Gbps PAM4 per channel. The Samtec FireFly™ Micro Flyover System™ copper and optical options offer a direct connection into the ASIC/FPGA package, bypassing the PCB for improved density and performance. The latest FireFly™ solutions are compatible with new generation FPGAs that support 56G PAM4 transceivers.

Technical Sessions (Taipei Location Only):

2:30 PM Tuesday, October 29, 2019 - Kevin Burt, Sr. Product Manager

- **Enable PCI Express® (PCIe®) 5.0 Specification System Design with Ethernet Architectures:** As PCI Express specification data rates increase to 32 GT/s, system SI becomes critical. As other interfaces (Ethernet, InfiniBand, etc.) achieve higher data rates, opportunities exist to leverage industry-wide techniques that optimize power, thermal efficiency and cost-effectiveness across the system. Samtec will explore options enabling PCIe system architects to achieve similar results.

The demonstrations can be seen in the Samtec booth at PCI-SIG Developers Conference Asia-Pacific Tour 2019. The first location is the Westin Tokyo on October 23, 2019. The second location is the Taipei Marriott Hotel on October 28-29, 2019.

For more information on the Samtec High-Performance Interconnect Portfolio, please visit www.samtec.com/s2s or e-mail SIG@samtec.com.

About Samtec, Inc.

Founded in 1976, Samtec is a privately held, \$822 MM global manufacturer of a broad line of electronic interconnect solutions, including High-Speed Board-to-Board, High-Speed Cables, Mid-Board and Panel Optics, Precision RF, Flexible Stacking, and Micro/Rugged components and cables. With 40+ locations serving approximately 125 countries, Samtec's global presence enables its unmatched customer service. For more information, please visit <http://www.samtec.com>.

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